



MAXIMUM CONTACT RESISTANCE:  
30 MILLIOHMS

DIALECTRIC WITHSANDING VOLTAGE:  
500V AC (SEA LEVEL)

MINIMUM INSULATION RESISTANCE:  
100 MEGAOHMS

**MATERIALS**

CONTACTS: COPPER ALLOY

SHELL: COPPER ALLOY

HOUSING: HIGH-TEMPERATURE  
THERMOPLASTIC

**FINISH**

CONTACTS: PLATED GOLD; TIN ON  
SOLDER TAILS

SHELL: COPPER ALLOY

**RECOMMENDED PCB LAYOUT**

|                                    |       |   |       |       |         |          |            |   |  |
|------------------------------------|-------|---|-------|-------|---------|----------|------------|---|--|
| <b>Ho Chien</b><br>www.hochien.com |       | DESCRIPTION: MINI USB B 5F R/A BLACK THROUGH HOLE |       |       |         |          |            |   |  |
|                                    |       | DATE  | UNIT  | MM    | DRAWING | PART NO. | MUSB-IIIIB |   |  |
| .X±0.15                            | X±5°  | CHECKED   | SCALE | 1 : 1 | DESIGN  |          |            |   |  |
| .XX±0.05                           | .X±2° | APPROVED  | VIEW  | ⊕ ⊖   |         | VERSION  | SHEET      | 1 |  |